AMENDMENTS TO THE CLAIMS

The claims in this listing will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS

1. (Previously Presented) An electronic component mounting method in which joints between a circuit substrate and electronic components are reinforced using a resin, the method comprising:

supplying an unhardened reinforcing resin on the circuit substrate;

printing a solder paste on the reinforcing resin such that the reinforcing resin is disposed between the solder paste and bond areas of the circuit substrate;

placing the electronic components, which have solder bumps, on the circuit substrate; and

heating the reinforcing resin, the solder bumps and the solder paste,

wherein the solder paste flows through the reinforcing resin and contacts the bond areas of the circuit substrate to interconnect the circuit substrate and the electronic components in response to heating of the reinforcing resin.

2. (Previously Presented) The electronic component mounting method according to claim 1,

wherein the reinforcing resin is a sheet-form resin, and the method further comprises cooling the reinforcing resin and the solder paste, thereby solder-bonding the electronic components on the circuit substrate and hardening the resin.

3. (Previously Presented) The electronic component mounting method according to claim 2, wherein the sheet-form resin includes equally spaced apertures forming a matrix of pores.

4. (Previously Presented) The electronic component mounting method according to claim 2, wherein the sheet-form resin includes recesses at positions that match electrode bond areas on the circuit substrate.

5. (Previously Presented) The electronic component mounting method according to claim 2, wherein the sheet-form resin includes holes at positions that match electrode bond areas on the circuit substrate.

6. (Previously Presented) An electronic component mounting method in which joints between a circuit substrate and electronic components are reinforced using a resin, the method comprising:

printing a solder paste on bond areas of the circuit substrate where electrodes of the electronic components are to be bonded; then

restricting fluidity of the solder paste so that the solder paste retains its shape as printed; then

applying a thermosettable reinforcing resin on the circuit substrate including the solder paste; then

placing the electronic components, which have solder bumps, on the circuit substrate; and then

solder-bonding the electronic components on the circuit substrate and hardening the reinforcing resin.

7. (Previously Presented) The electronic component mounting method according to claim 6, while restricting fluidity of the solder paste, the fluidity is controlled such that the solder paste retains its shape as printed during the application of the reinforcing resin but deforms when a load is applied when the electronic components are mounted.

8. (Previously Presented) The electronic component mounting method according to claim 7, while restricting the fluidity of the solder paste, the solder paste is dried so as to volatilize the solvent or the like in the solder paste.

9. (Previously Presented) The electronic component mounting method according to claim 8, wherein the solder paste covering a substantially entire area on the circuit substrate or covering a specified area is selectively dried.

10. (Previously Presented) The electronic component mounting method according to claim 8, wherein drying is carried out using any of hot air, a heater, microwave, and light or using vacuum drying method.

11. (Previously Presented) The electronic component mounting method according to claim 6, wherein the reinforcing resin is applied on a substantially entire area of the circuit substrate or on a specified area selectively.

12. (Previously Presented) The electronic component mounting method according to claim 6, wherein the reinforcing resin is a resin material having a flux effect.

13. (Previously Presented) The electronic component mounting method according to claim 6, wherein the reinforcing resin is used that has an effect of bonding the electronic components to the circuit substrate.

14. (Previously Presented) The electronic component mounting method according to claim 6, wherein the mounted electronic components are retained by deformation of the solder paste that deforms by a mounting load and by adhesive power of the reinforcing resin.

15-19. (Cancelled)

20. (New). An electronic component marking method in which joints between a circuit substrate and electronic components are reinforced using a resin, the method comprising:

supplying an unhardened reinforcing resin on the circuit substrate, the reinforcing resin comprising a sheet form resin, wherein an adhesive power of one side of the sheet form resin is higher than an adhesive power of an opposite side of the sheet form resin;

printing a solder paste on the reinforcing resin such that the reinforcing resin is disposed between the solder paste and bond areas of the circuit substrate;

placing the electronic components, which have solder bumps, on the circuit substrate;

heating the reinforcing resin, the solder bumps, and the solder paste such that the solder paste flows through the reinforcing resin and contacts the bond areas of the circuit substrate to interconnect the circuit substrate and the electronic components in response to heating of the reinforcing resin; and

cooling the reinforcing resin and the solder paste to thereby solder bond the electronic components on the circuit substrate and to harden the resin.

21. (New). The electronic component marking method according to claim 20, the adhesive power of a first side of the sheet form resin contacting the substrate being higher then the adhesive power of an opposite side of the sheet form resin.

22. (New). The electronic component mounting method according to claim 20, wherein the sheet form resin includes equally spaced apertures providing a matrix of pores.

23. (New). The electronic component mounting method according to claim 20, wherein the sheet form resin includes recesses at positions that match electrode bond areas provided on the circuit substrate.

24. (New). The electronic component mounting method according to claim 20, wherein the sheet form resin includes holes at positions that match electrode bond areas provided on the circuit substrate.